

Resistance											
One Step Cure	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
Room Temp. Stability	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
Withstands 350 C											✓
Package Sealing											

TYPICAL APPLICATIONS

[4030LD](#) [4030SM](#) [4130SM](#) [4130HT](#) [4131HT](#) [5030P](#) [5130P](#) [6030Hk](#) [6030Hk-PT](#) [6030Hk-SD](#) [6030SF](#) [3030](#)

General Die Bonding	✓			✓		✓	✓	✓	✓	✓	✓
High k Interface	✓			✓	✓	✓	✓	✓	✓	✓	✓
High Power	✓			✓	✓	✓	✓	✓	✓	✓	✓
Large CTE mismatch	✓	✓	✓	✓	✓	✓					
Large Area Attach	✓			✓		✓					
Direct Bond to Metal	✓			✓	✓	✓	✓	✓	✓		✓
High Temp. Wire Bond						✓	✓	✓	✓		✓
Multichip Modules	✓			✓	✓	✓	✓	✓	✓		✓
Hybrids	✓	✓	✓	✓	✓	✓	✓	✓		✓	✓
Chip-on-Board	✓	✓	✓	✓							
Surface Mount Passives		✓	✓								
Automotive		✓	✓	✓	✓	✓	✓	✓		✓	✓
Hi Rel. / Military		✓	✓	✓		✓		✓			✓